CareerCross by JAC Recruitment

PR/095215 | R&D Manager - PCB

募集職種

人材紹介会社
ジェイ エイ シー リクルートメント シンガポール

求人ID
1540537

業種
電気・電子・半導体

雇用形態
正社員

勤務地
シンガポール

給与
経験考慮の上、応相談

更新日
2025年06月04日 09:01

応募必要条件

職務経験
3年以上

キャリアレベル
中途経験者レベル

英語レベル
ビジネス会話レベル

日本語レベル
ビジネス会話レベル

最終学歴
短大卒： 準学士号

現在のビザ
日本での就労許可は必要ありません

募集要項

Company and Job Overview

Our client is a leading PCB manufacturer. We are looking for an R&D Manager to develop advanced PCB technologies, materials, and processes to enhance product performance, reliability, and manufacturability.

Responsibilities

Research and develop new PCB materials, stack-ups, and manufacturing processes to improve performance, cost efficiency, and reliability.

Design and optimize high-speed, high-frequency, HDI (High-Density Interconnect), and rigid-flex PCBs for various applications.

Conduct feasibility studies, simulations (signal integrity, thermal, EMI/EMC), and prototyping to validate new designs and technologies.

Collaborate with PCB fabrication, assembly, and testing teams to ensure manufacturability and quality standards.

Stay updated with industry trends, emerging technologies (e.g., embedded components, advanced substrates), and IPC standards.

Troubleshoot and resolve technical challenges related to PCB design, fabrication, and assembly.

Work with customers and suppliers to define technical requirements and develop customized solutions.

Document R&D findings, prepare technical reports, and present recommendations to stakeholders.

Support patent applications and intellectual property development for innovative PCB technologies.

Qualifications & Experience:

Education: Bachelor's/Master's degree in Electrical/Electronics Engineering, Chemistry/Chemical engineering, Materials Science, Mechanical Engineering, or related field.

Preferably 1-3 years in management of PCB design, fabrication, or R&D (experience with high-frequency/RF, High speed PCBs is a plus).

Knowledge of IPC standards, DFM (Design for Manufacturability), and signal integrity analysis and familiarity with high laminate such as low loss dielectrics is a strong plus

Familiarity with AI/ML applications in PCB design

Experience with thermal management, EMI shielding, or embedded passive/active components.

Knowledge of additive manufacturing (3D printing) for PCBs

Catherine Qu
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#LI-JACSG
#countrysingapore

会社説明